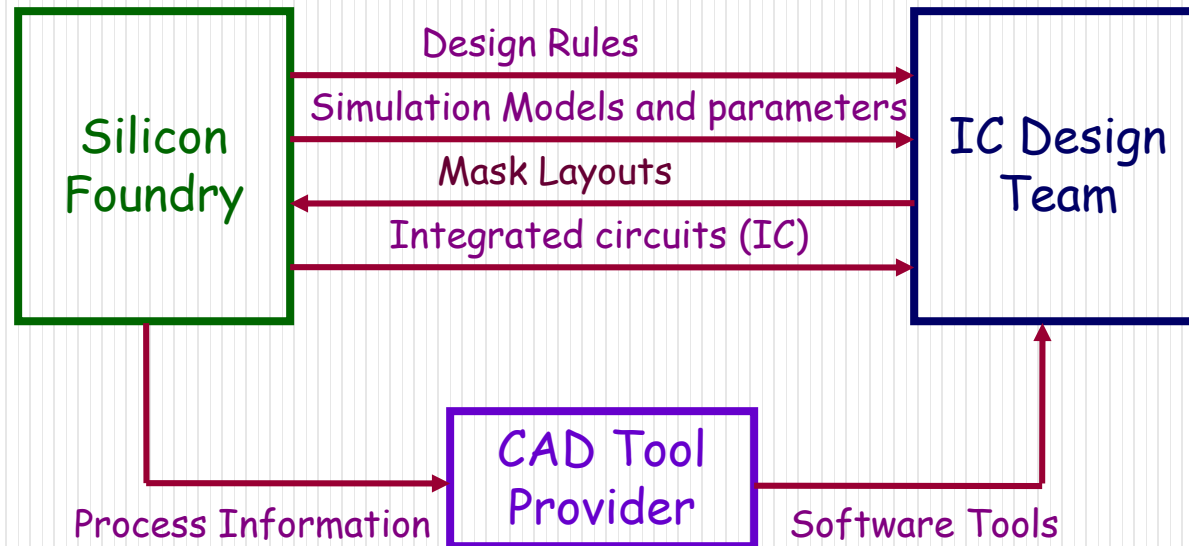


CSEN 1040 Advanced ES

Architectural Choices

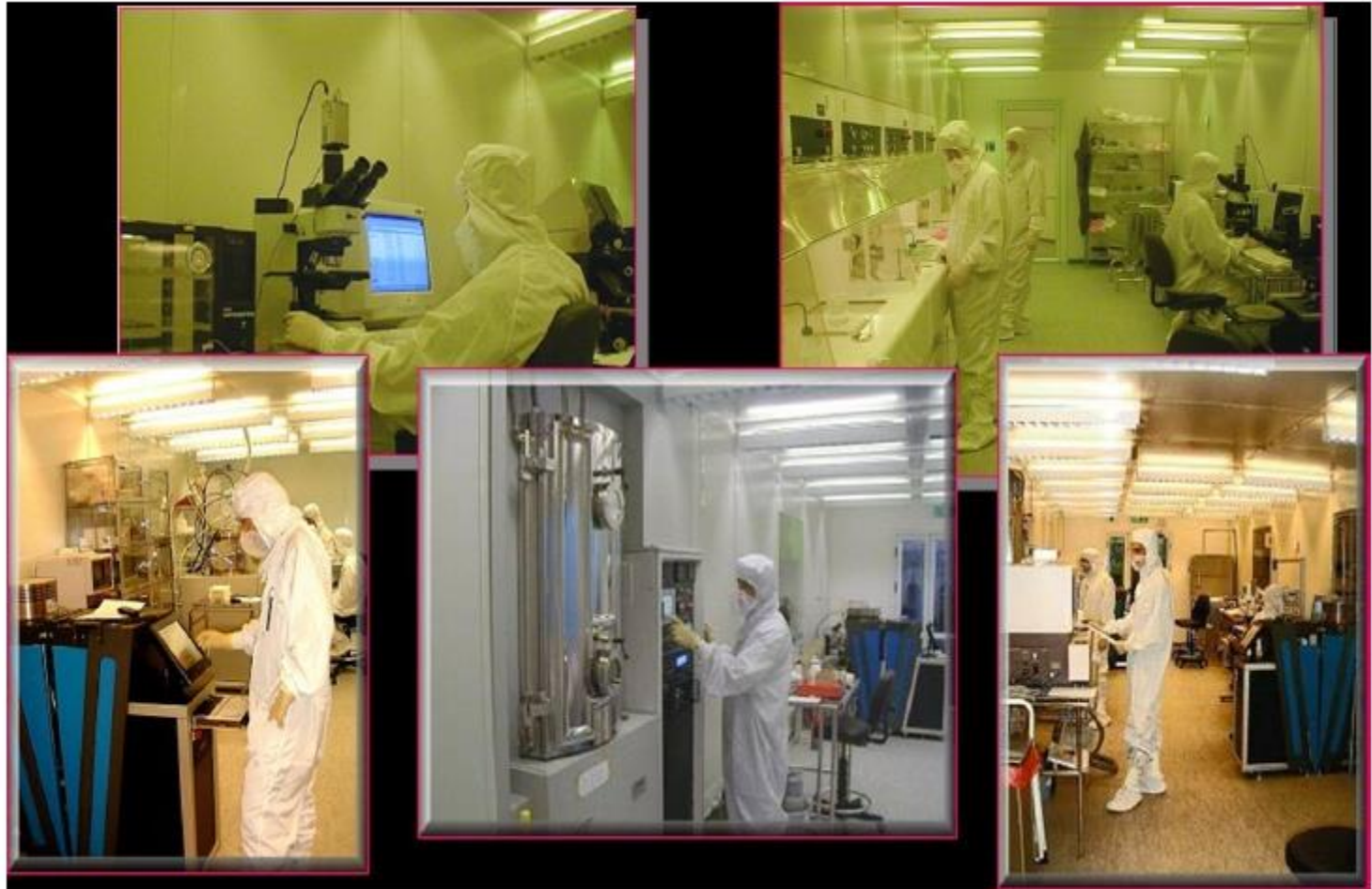
Prof. Ayman Elnaggar

VLSI Design Methodology



Relationship between a silicon foundry,
an IC design team and a CAD tool provider

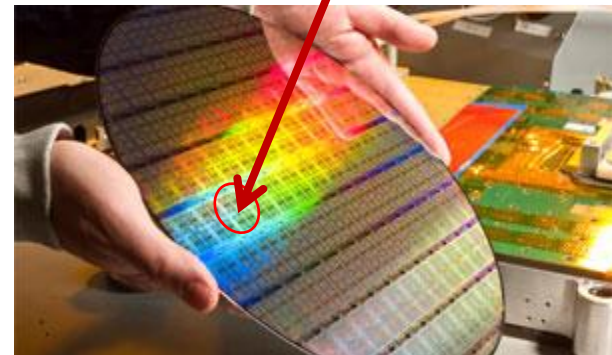
How Does an IC Fabrication Lab look like?



IC Manufacturing

- ICs are typically created on larger circular sheets of silicon called “wafers”
- A wafer is typically 100-300 mm in diameter, and about 4 mm thick
- A large silicon circuit is about 1 cm long
- In order to fabricate a number of chips, the wafer passes through thousands of steps including: thermal, chemical, cleaning, ... etc
- Each IC is tested before and after “packaging”

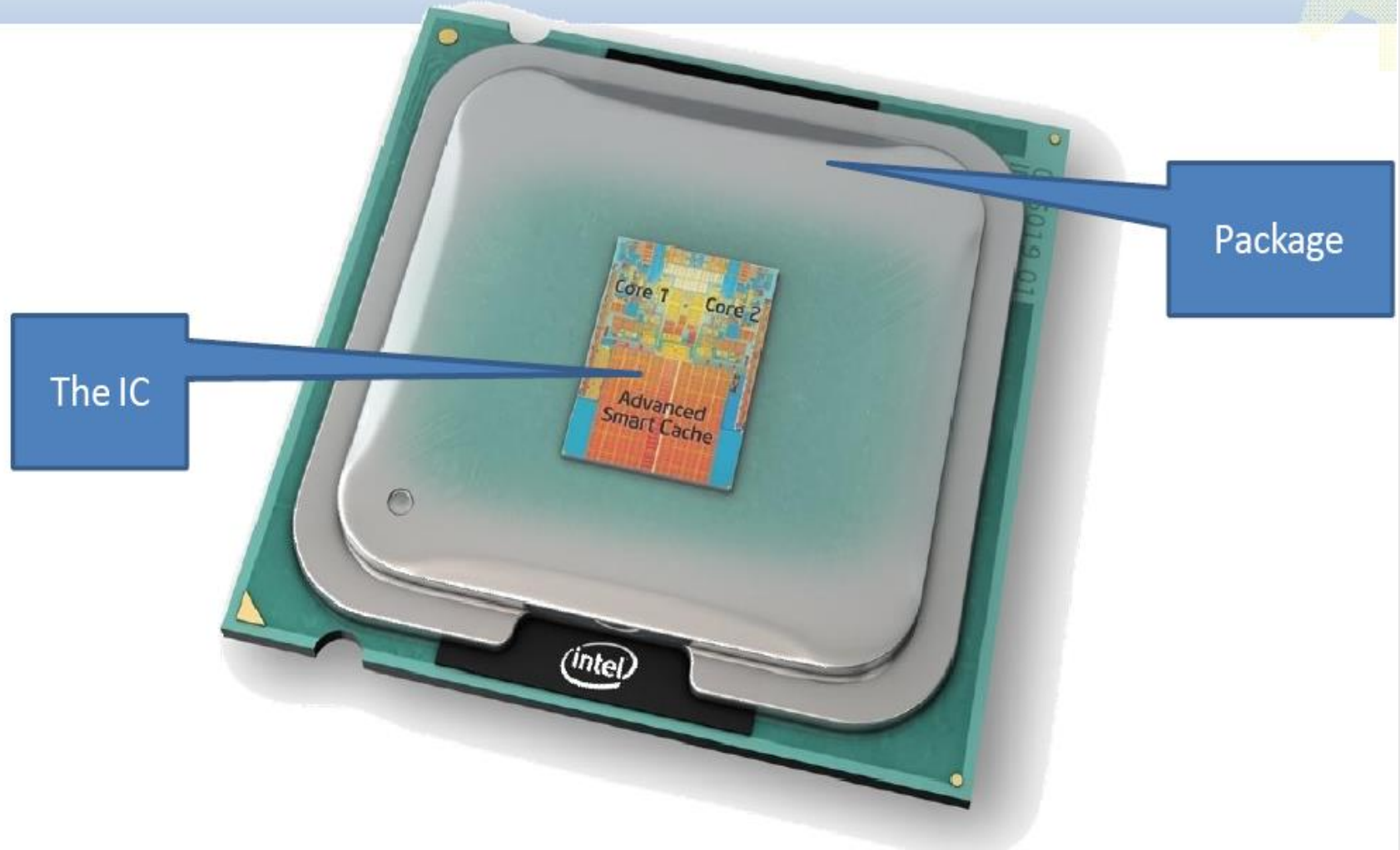
A Single “Die” or “Chip”



**A 300mm IBM Power-7 (8-Core)
Server-Class Processor Wafer**

What does an IC look like?

Intel dual core

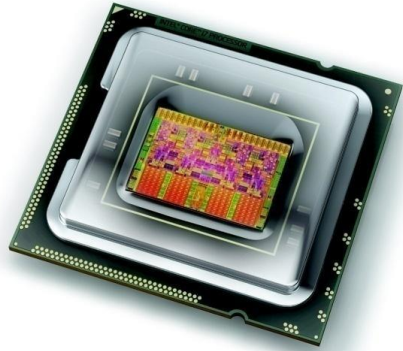
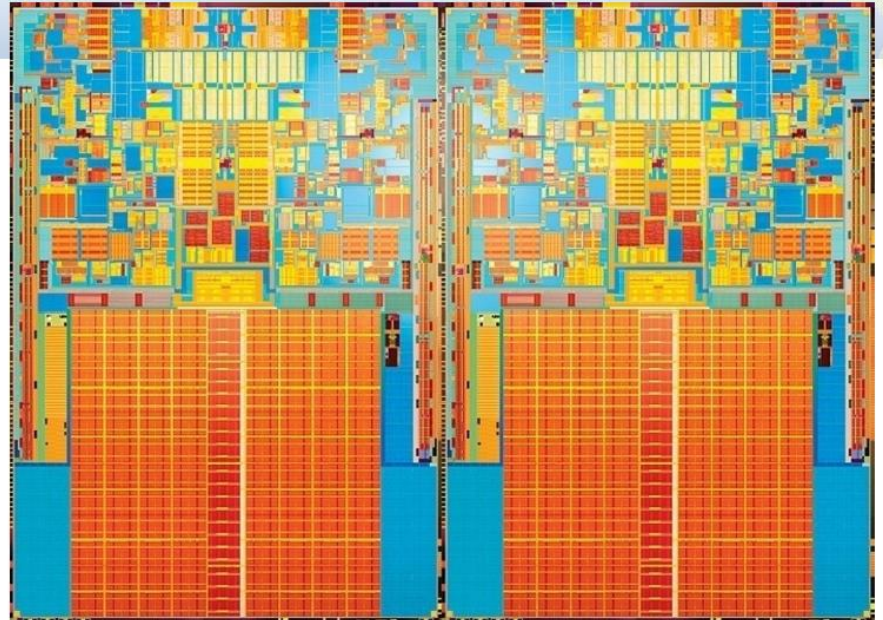


What does an IC look like?

45 nm, quad-core

Note the symmetry

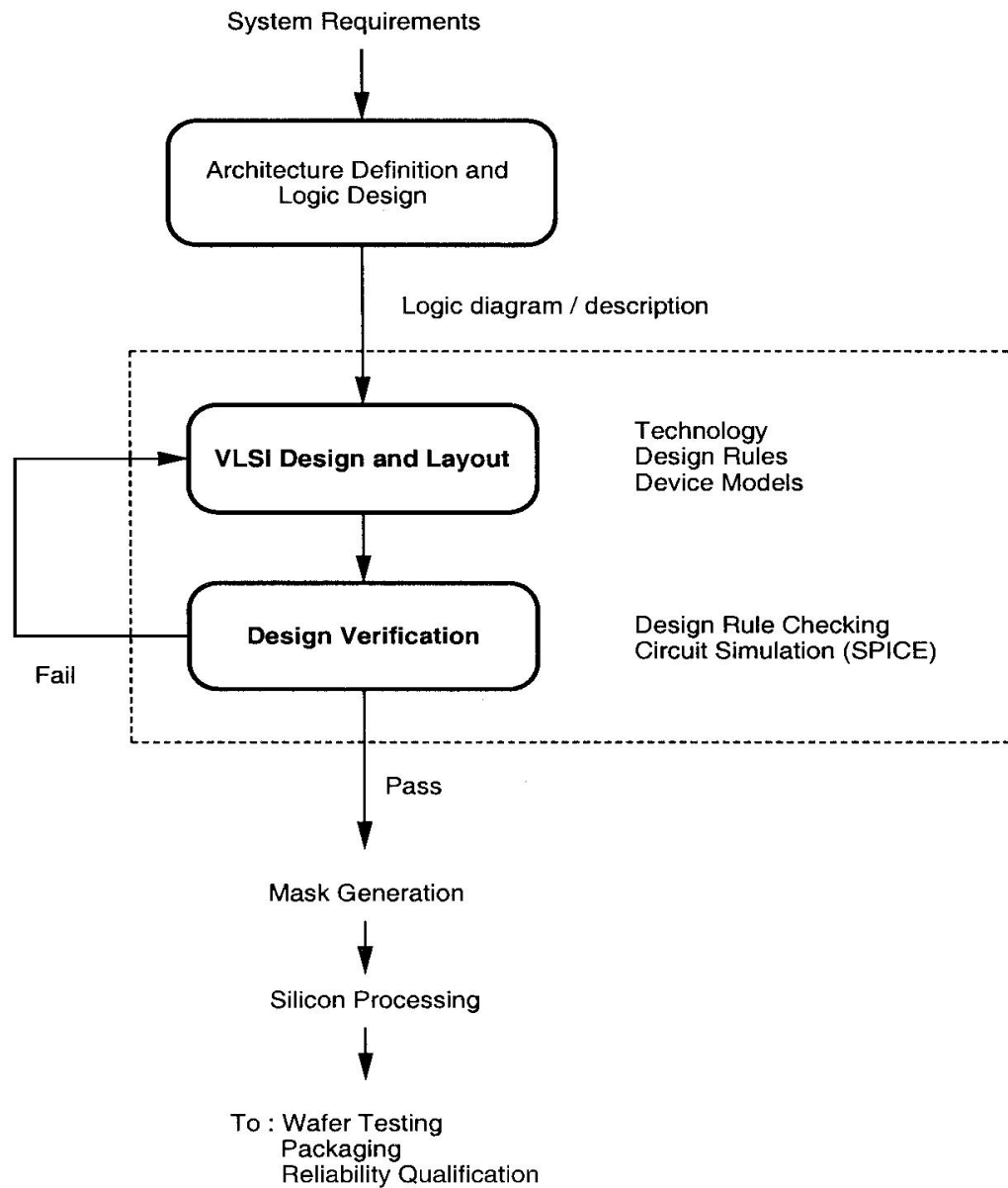
Two dual-cores integrated



Pinless Chip!!

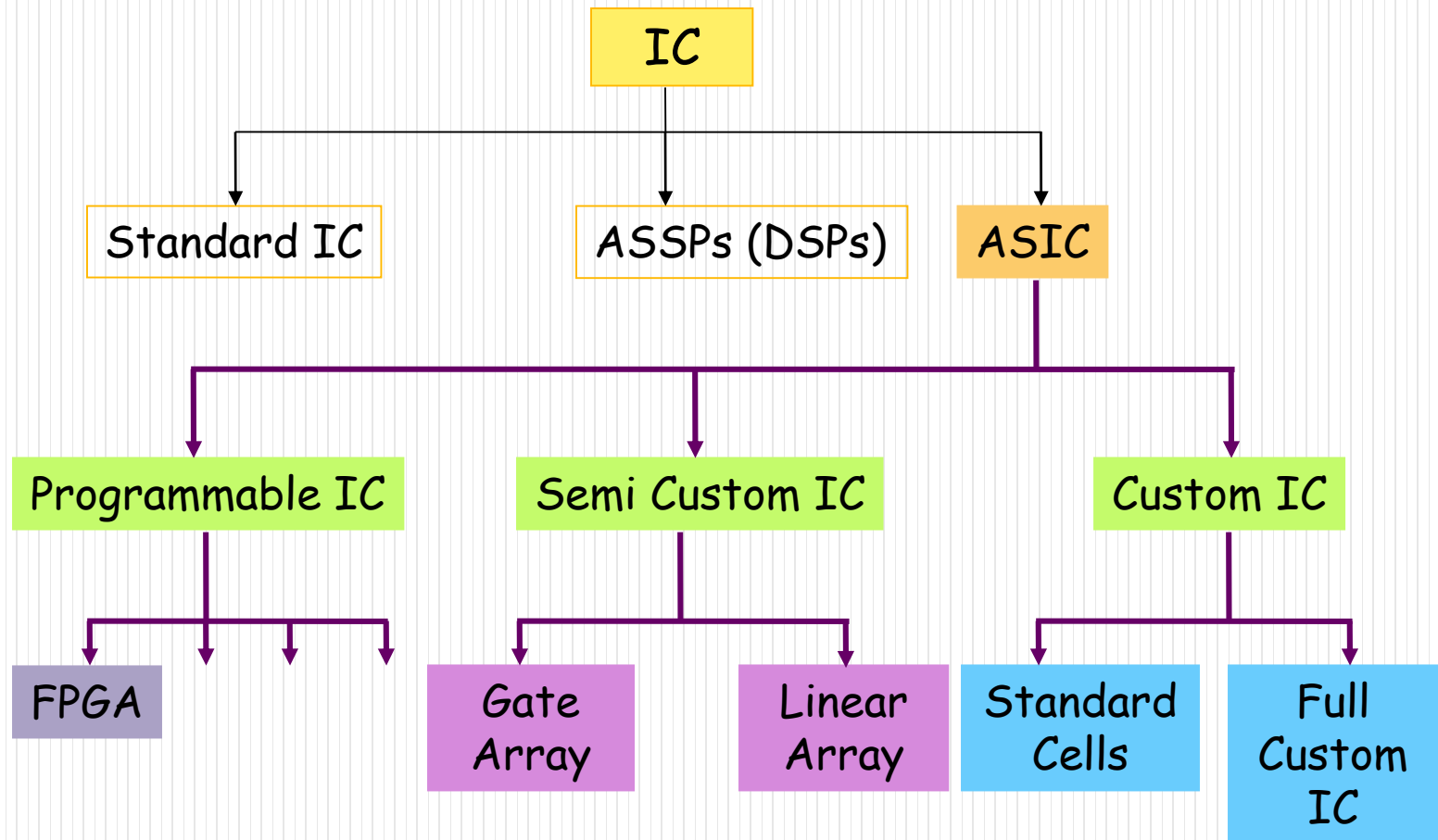


Bottom view showing the gold contacts

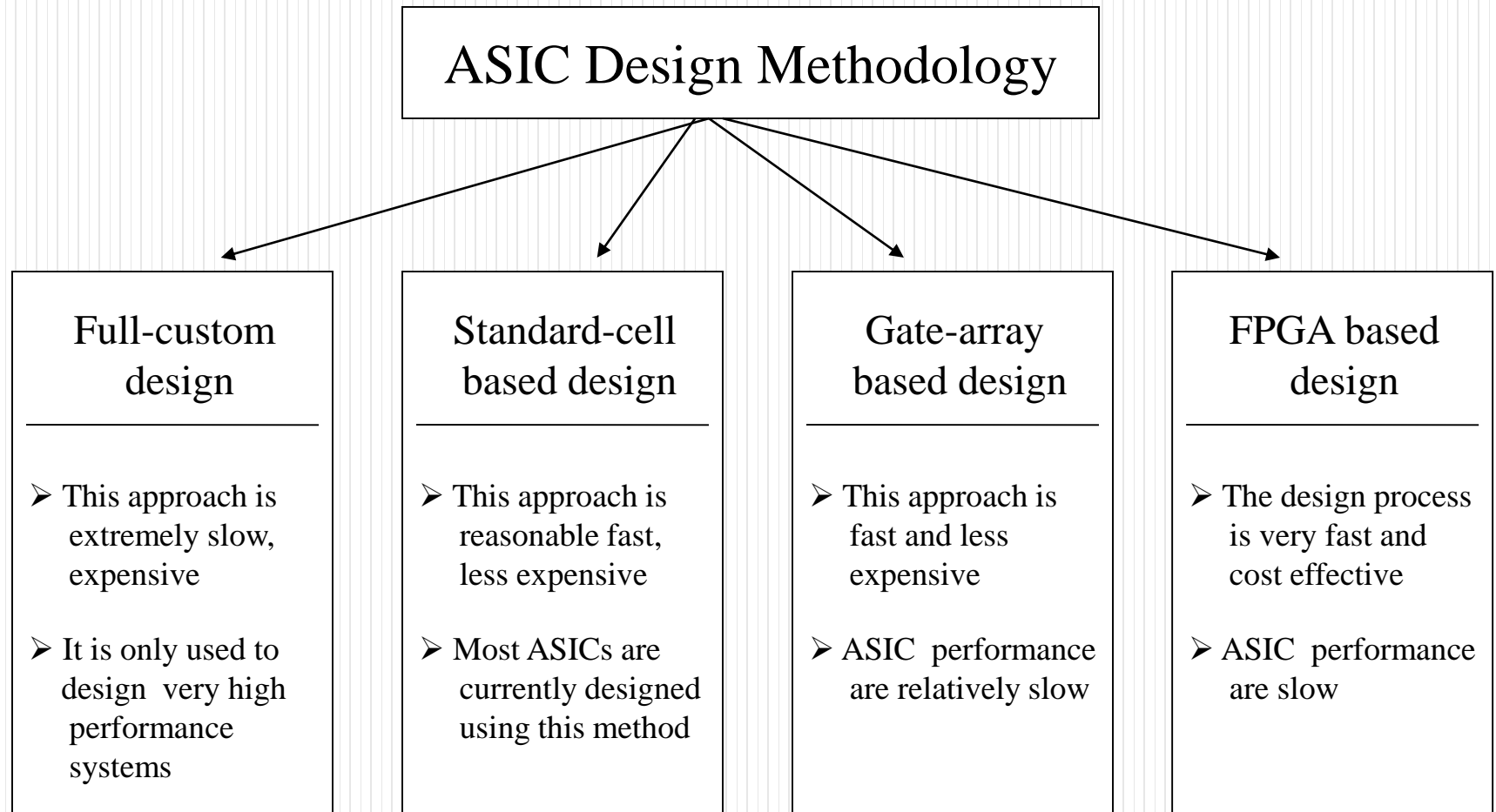


The flow of circuit design procedures.

Application Specific Integrated Circuits (ASICs)



ASIC Design Methodologies



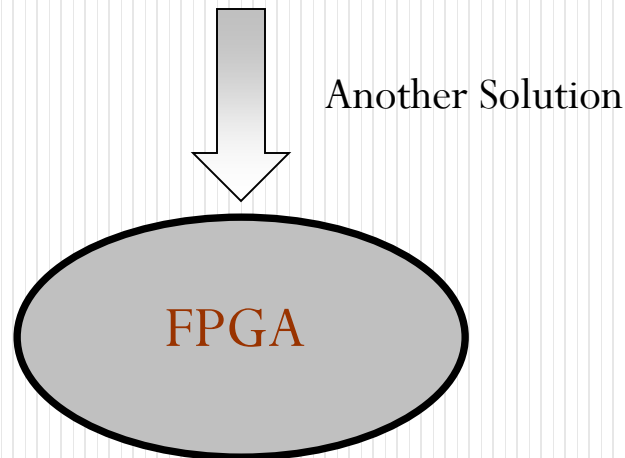
Custom ICs-Benefit

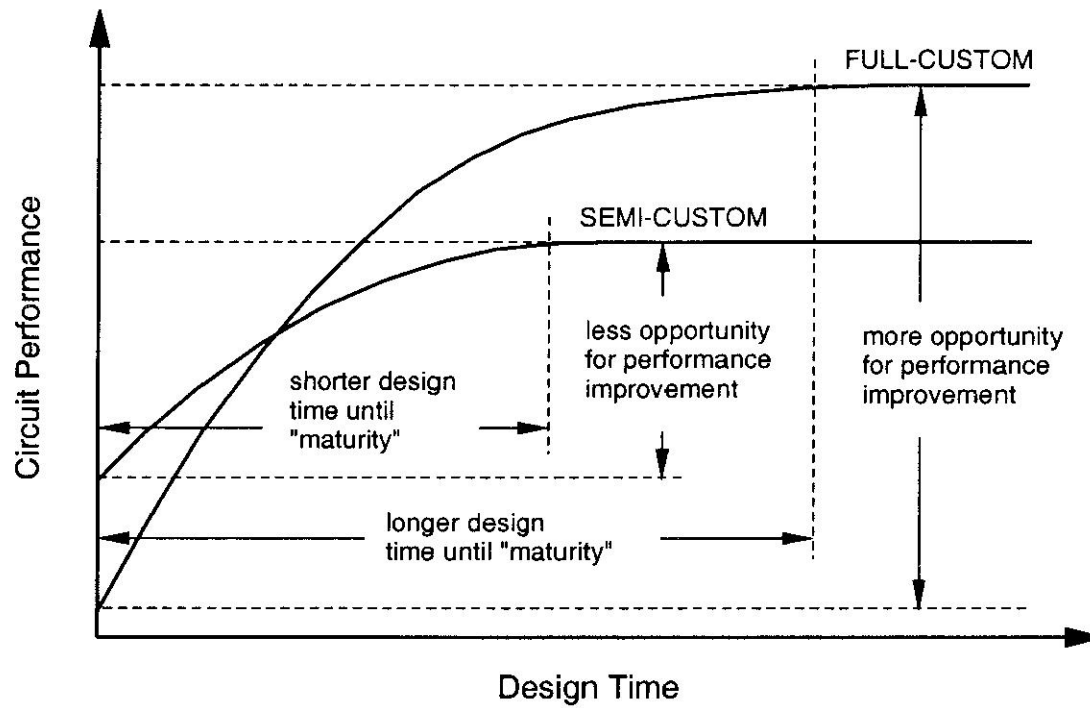
- Improve cost/performance
- Reduce power consumption
- Mixed Analog and Digital Designs
- Design optimization through IC manufacturing process
- Development Tools support HDL and Schematic design approach



Custom ICs -Drawbacks

- Large development cost
- Inflexible design
- Deployed systems can not be upgraded
- Mistakes in product development are costly
- Updates requires a redesign
- Complex and expensive development tools





Impact of different VLSI design styles upon the design cycle time and the achievable circuit performance.

Why Programmable Logic?

- Facts:
 - It is most economical to produce an IC in large volumes
 - Many designs required only small volumes of ICs
- Need an IC that can be:
 - Produced in large volumes
 - Handle many designs required in small volumes
- A programmable logic part can be:
 - made in large volumes
 - programmed to implement large numbers of different low-volume designs

Programmable Logic - Additional Advantages

- Many programmable logic devices are *field-programmable*, i. e., can be programmed outside of the manufacturing environment
- Most programmable logic devices are *erasable* and *reprogrammable*.
 - Allows “updating” a device or correction of errors
 - Allows reuse the device for a different design - the ultimate in re-usability!
 - Ideal for course laboratories
- Programmable logic devices can be used to prototype design that will be implemented for sale in regular ICs.
 - Complete Intel Pentium designs were actually prototype with specialized systems based on large numbers of VLSI programmable devices!

Programming Technologies

- Programming technologies are used to:
 - Control connections
 - Build lookup tables
 - Control transistor switching
- The technologies
 - Control connections
 - Mask programming
 - Fuse
 - Antifuse
 - Single-bit storage element

Programming Technologies

- The technologies (continued)
 - Build lookup tables
 - Storage elements (as in a memory)
 - Transistor Switching Control
 - Stored charge on a floating transistor gate
 - Erasable
 - Electrically erasable
 - Flash (as in Flash Memory)
 - Storage elements (as in a memory)

Technology Characteristics

- Permanent - Cannot be erased and reprogrammed
 - Mask programming
 - Fuse
 - Antifuse
- Reprogrammable
 - Volatile - Programming lost if chip power lost
 - Single-bit storage element
 - Non-Volatile
 - Erasable
 - Electrically erasable
 - Flash (as in Flash Memory)

Technology Characteristics

- Reprogrammable (Cont.)
 - Build lookup tables
 - Storage elements (as in a memory)
 - Transistor Switching Control
 - Stored charge on a floating transistor gate
 - Erasable
 - Electrically erasable
 - Flash (as in Flash Memory)
 - Storage elements (as in a memory)

Technology Breakthrough Impacts Windows-Compatible Hardware Market

- Field Programmable Gate Arrays (FPGAs) break through price/capability barriers
 - 1 million gates drop from \$200+ to <\$10
 - 90nm will offer another >2X improvement
 - 32 bit RISC processors “for free”
- Embedded “soft” 32-bit processors debut allowing complete System-on-Chip designs
- Previously relegated to high-margin/low-volume applications



Why Should We Care?

Cost-effective FPGAs Enable New Windows-Compatible Products

Greater product differentiation

Functionality and performance never available at this price point

Shorter development cycles = faster time to market

Improved product flexibility = longer market life

Reduced part inventory

More product variants

New Low-Cost Technologies

FPGA Families

Altera: Cyclone

Xilinx: Spartan 3

QuickLogic: QuickMIPS,
Eclipse II

Actel: ProASIC Plus

Embedded Processors

Altera: Nios

Xilinx: MicroBlaze

QuickLogic: MIPS

Actel: 8051

Full-custom ICs Versus FPGA Comparison

Tooling cost

Non-recurring engineering costs (NRE)

Time to market

Product risk

Product flexibility

Inventory



Non-Recurring Engineering (NRE)

Full-Custom Designs

- NRE is very high
- Each subsequent re-spin costs another NRE
- For new 90nm technology NRE > \$1M
- High-risk methodology requiring massive volume to recoup costs

FPGA Designs

- No NRE charges
- Some cost-reduction available by ASIC conversion with minimal (<\$100K) NRE

Cost of FPGA device is offset by NRE in all but the highest volume applications

Time To Market

- Full-Custom Designs
 - Typical design cycle 12-18 months, minimum 9 months
 - Additional re-spins add 8-10 weeks each
- FPGA Designs
 - Typical design cycle 4 months
 - Re-spins not an issue

Extremely Fast Time-To-Prototype

Software-based prototype in days

System assembly on FPGA in minutes with processor, memory, bus, interfaces, peripherals

C/C++ based application (with RTOS if needed) running in minutes using actual hardware

Iterative development/refinement flow

Performance-critical routines easily migrated to “hardware” implementations

Software development in parallel with working hardware

Embedded “virtual instrumentation” offers in-circuit debugging

Allows evolutionary design style



Benefits Of FPGA-Based Design

- Improved product flexibility
 - Changes hardware/software up to (and even after) deployment
 - Inventoried parts can be re-deployed in multiple applications
 - More product variants on single platform
 - Upgrade/enhance in the field
- Reduce inventory
 - Single part for multiple variations and versions of product

What's Needed For FPGA-Based Product Development?

- Complete toolsets provided by FPGA vendors

- Robust libraries of pre-tested IP components

- Processor cores (8,16,32 bit configurable)

- Peripherals (USB, PCI, I/O, DSP, ethernet, Memory...)

- Ready-to-use development prototyping boards for a variety of application types

- Development environments are PC/Windows-based, no UNIX workstations required

DSP Processors

Architecture and Examples

What is Real-Time Digital Signal Processing?



Time-constrained Operation or Transformation performed on *digital* signals within a required period of time to maintain synchronization with occurring events.

- Example:
 - Processor clocked at 120 MHz and can perform 120MIPS
 - Sampling rate = 48KHz (Digital Audio Tape - DAT) number of instructions per sample = $(120 \times 10^6) / (48 \times 10^3) = 2500$.
 - Sampling rate = 8KHz (voice-band, telephony) number of instructions per sample = 15000.
 - Sampling rate = 75MHz (CIF 360x288 Video at 30 frames per second) number of instructions per sample = 1.6.

Real-Time Digital Signal Processing

- Constraints:
 - real-time DSP applications limited to cases where the required sampling rate is sufficiently lower than the processor's instruction rate
- Challenge:
 - Produce working code.
 - Produce sufficiently compact code to execute in real-time.
 - A sufficient number of instructions need to be performed between sample periods.



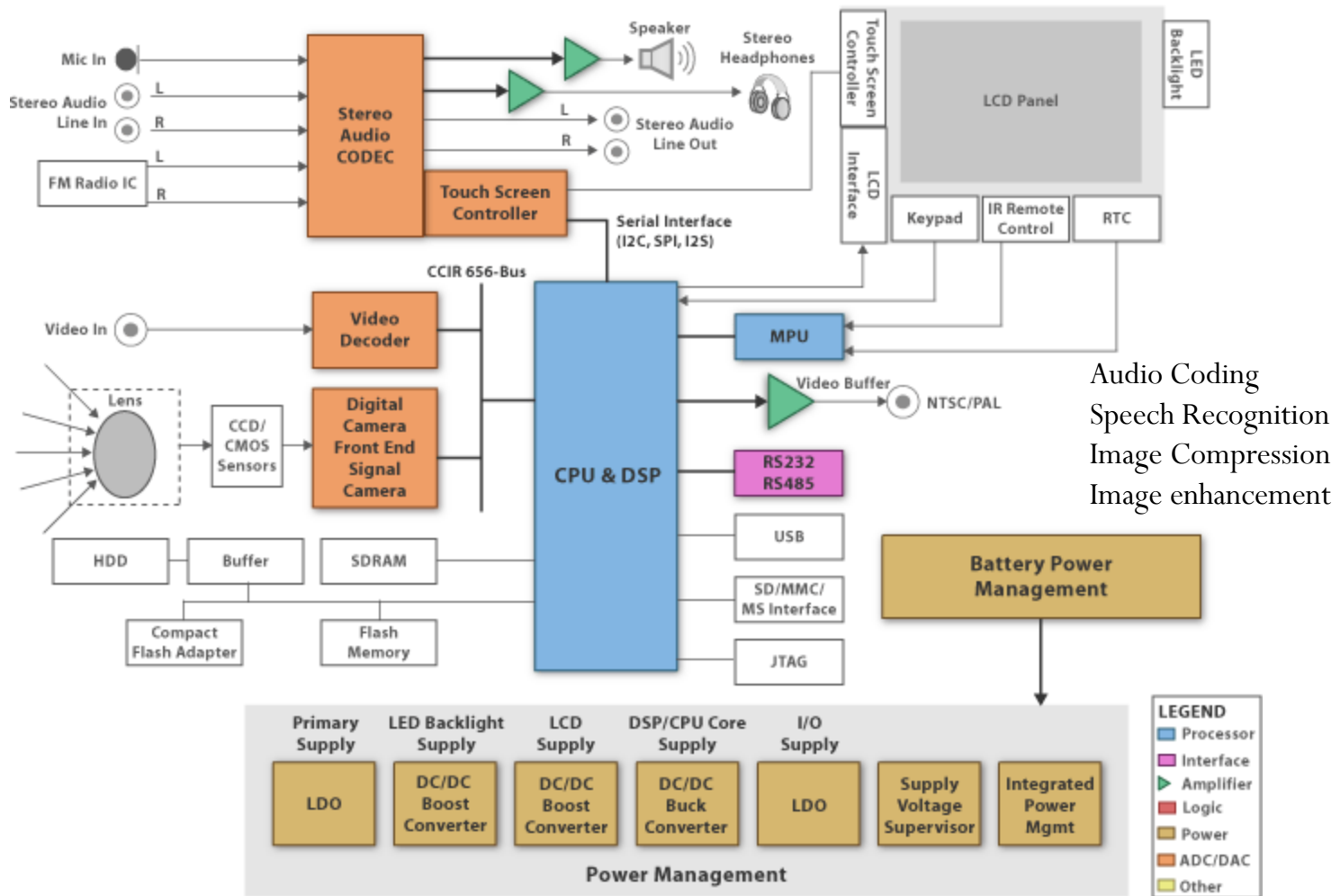
What are DSP Processors?

- Microprocessor specifically designed to perform fast DSP operations (e.g., Fast Fourier Transforms, inner products, Multiply & Accumulate)

Why Go Digital?

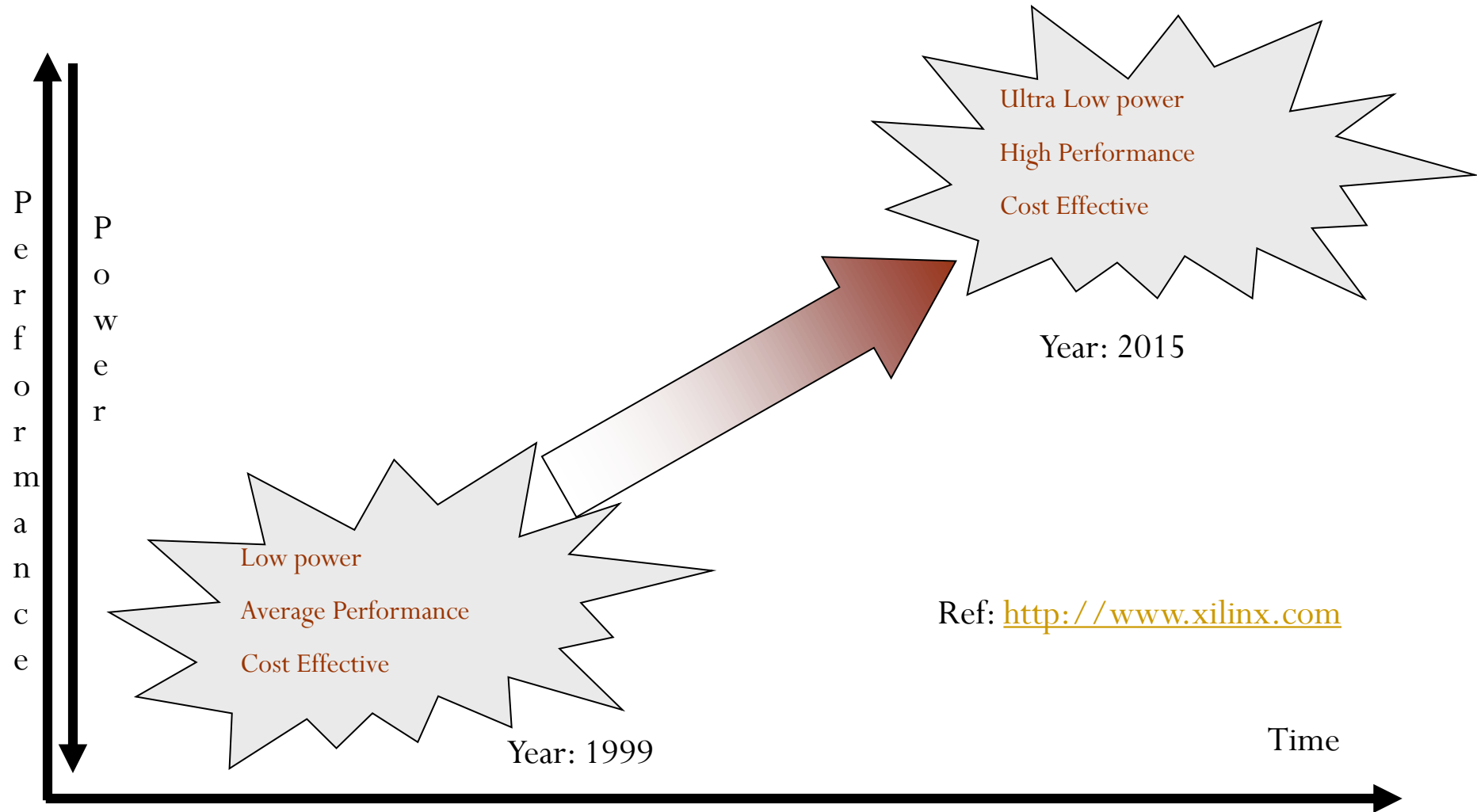
- Programmability
 - One hardware can perform several tasks.
 - Upgradeability and flexibility.
- Repeatability
 - Identical performance from unit to unit.
 - No drift in performance due to temperature or aging.
- Immune to noise
- Offers higher performance : CD players versus phonographic turntable

TYPICAL PORTABLE MEDIA DEVICES



Web Link: <http://focus.ti.com/vf/docs/blockdiagram.tsp?blockDiagramId=6046&appId=267>

Portable Applications – Need High Performance Processors



What is Special about Signal Processing Applications?

- Large number of samples being continuously fed to the system (samples or blocks).
- Repetitive Operations:
 - The same operation being applied to different set of samples
 - Parallel processing
- Vector and Matrix Operations
- Real time operations

Example: Digital Filtering

- The two most common real-time digital filters are:
 - Finite Impulse Filter (FIR)
 - Infinite Impulse Filter (IIR)
- The basic FIR Filter equation is

$$y[n] = \sum h[k].x[n - k]$$

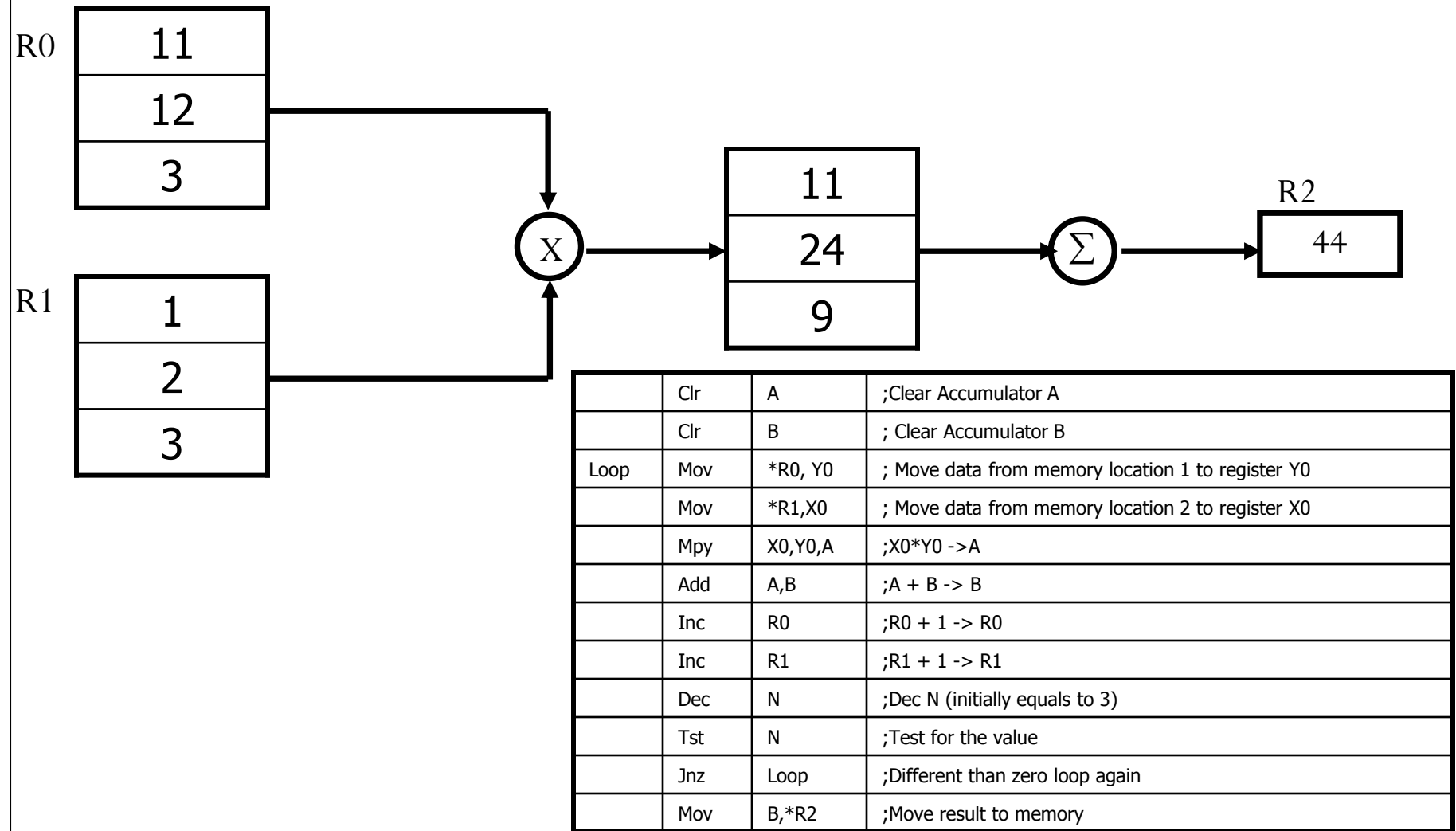
where $h[k]$ is an array of constants

In C language

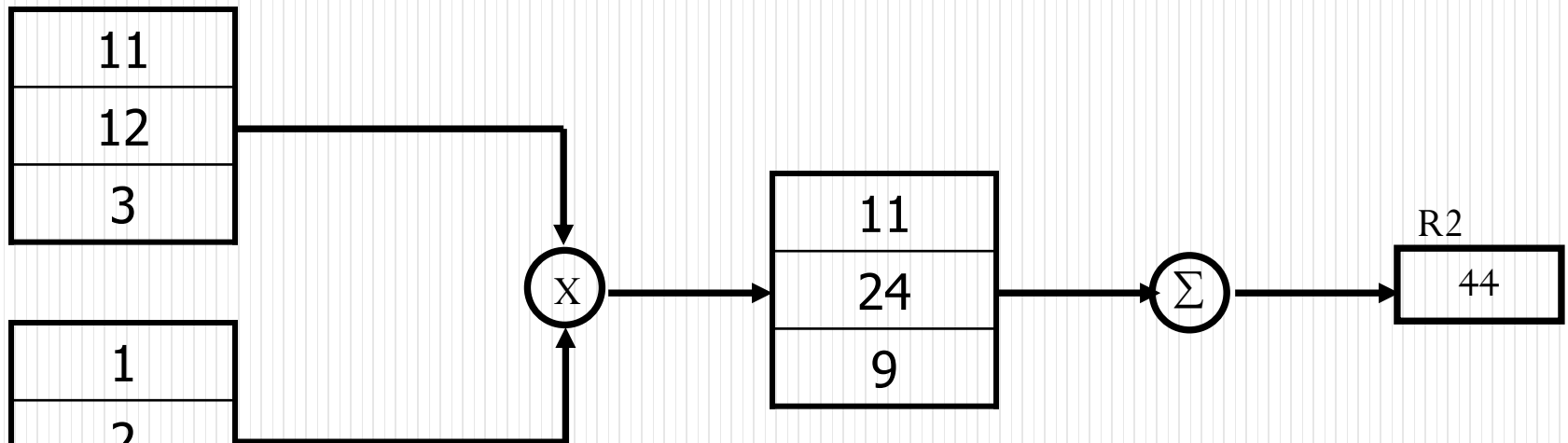
```
y[n]=0;
For (n=0; n<N;n++)
{
  For (k = 0;k<N;k++)
    //inner loop
    y[n] = y[n] + h[k]*x[n-k];}
```

Only Multiply and
Accumulate (MAC)
is needed!

Using General Purpose Processor (GPP)



Using DSP



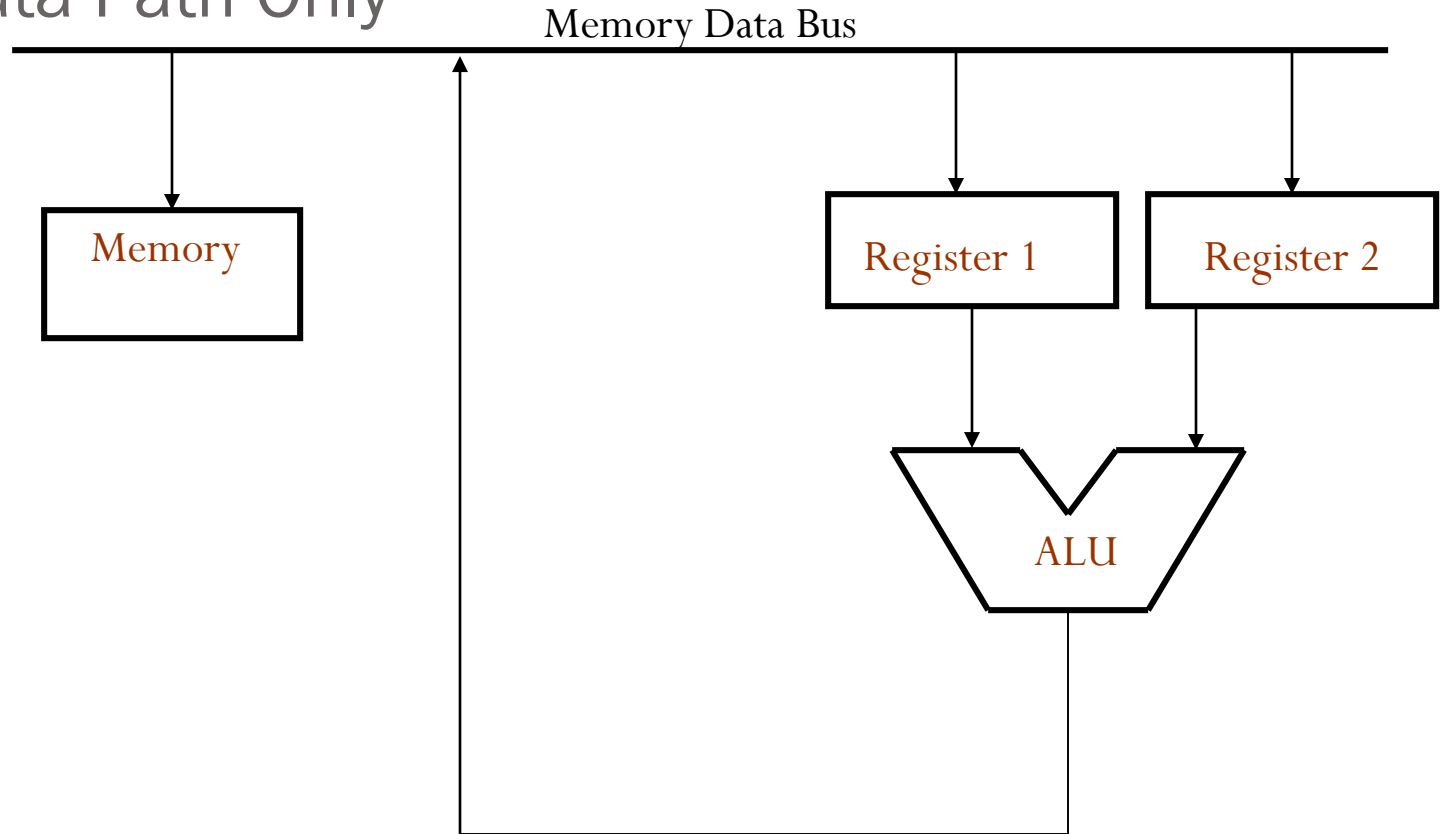
	Clr	A	;Clear Accumulator A
	Rep	N	; Rep N times the next instruction
	MAC	*(R0)+, *(R1)+, A	; Fetch the two memory locations pointed by R0 and R1, multiply them together and add the result to A, the final result is stored back in A
	Mov	A, *R2	; Move result to memory

GPP Drawbacks

- More instructions/task
- Common Memory for data and program
 - Limited bus/memory bandwidth

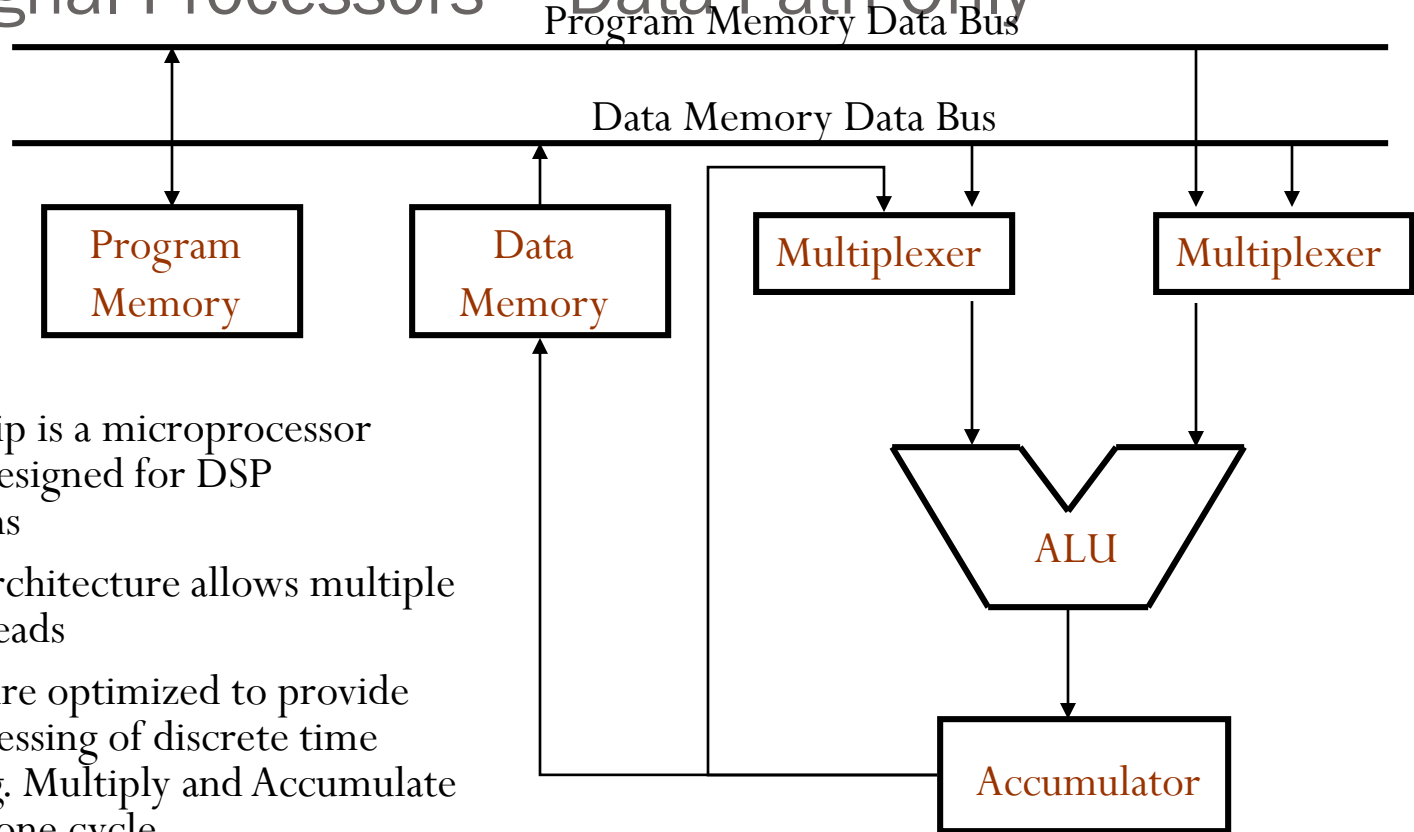
Solution : DSP Architectures

GPP – Data Path Only



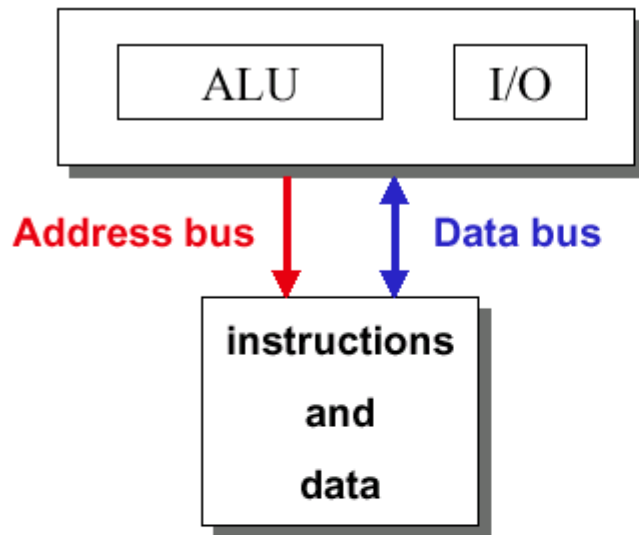
Same memory for program and data

Digital Signal Processors – Data Path Only

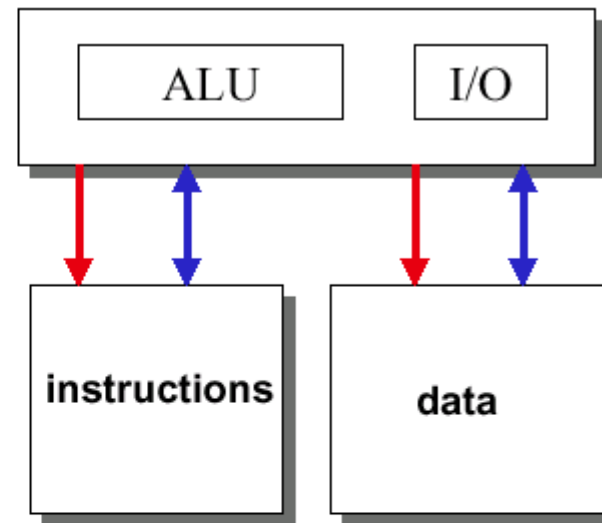


- A DSP Chip is a microprocessor specially designed for DSP applications
- Harvard architecture allows multiple memory reads
- Architecture optimized to provide rapid processing of discrete time signals, e.g. Multiply and Accumulate (MAC) in one cycle

Memory structures



Von Neuman architecture
Area efficient but requires higher bus bandwidth because instructions and data must compete for memory.



Harvard architecture was coined to describe machines with separate memories. **Speed efficient:** Increased parallelism.

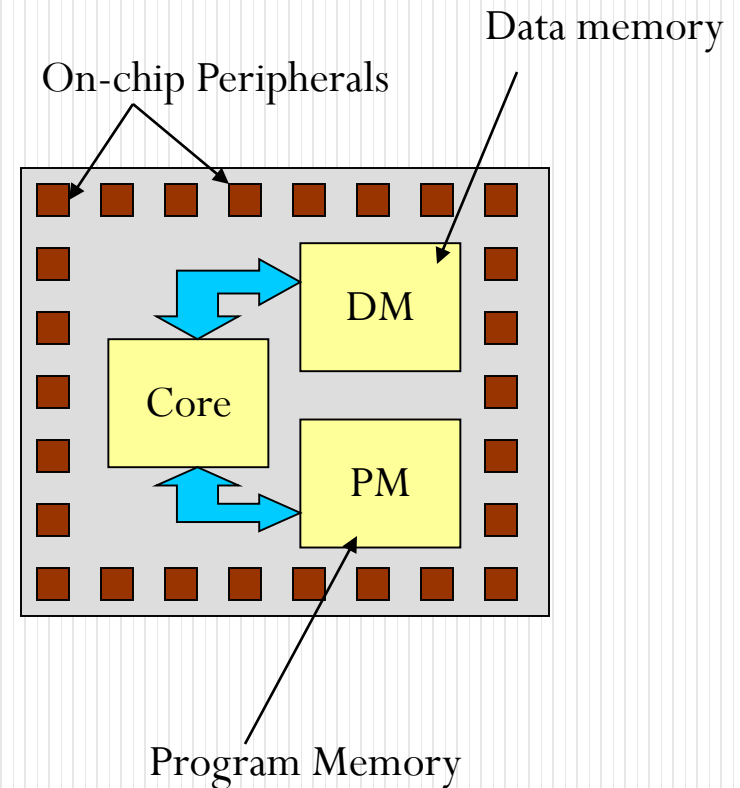
DSP versus GPP

- Multiple parallel units
 - multiply accumulate (possibly several units)
 - address calculation in parallel to processing
 - barrel shifter
- Memory Access
 - special ALU for address calculation
 - Bit reversed addressing
 - circular addressing
- Automatic loops
 - Software looping: writing assembly code to perform branching
 - Hardware looping: dedicated hardware loop counter register
- Hardware support for managing arithmetic computation (in GPP it needs multiple cycles)
 - Shifters
 - Guard bits
 - Saturation

Preventing
Overflow!!

Digital Signal Processor (DSP) - Overview

- DSP Core includes:
 - Address buses
 - Data buses
 - Data arithmetic logic unit (ALU)
 - Address generation unit (AGU)
 - Program controller
 - Bit-manipulation unit
 - Enhanced debugging module
- Peripherals on chip
 - Timer
 - serial link
 - communication links
 - DSP to DSP
 - Ethernet
 - ATM
 - host ports
 - input/output pins
- Adaptation for FFT
 - bit reverse addressing
- Special instructions
 - Parallel move support
 - Loop instructions; special hardware instructions (e.g., FIR)



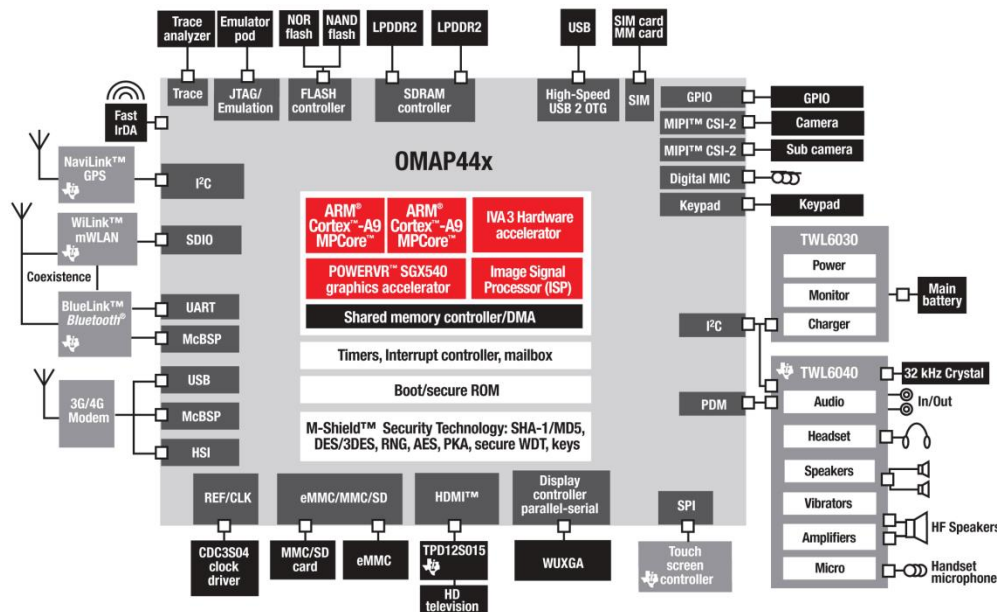
Enhancing DSP Architectures

- More parallelism
 - Increase the number of operations that can be performed in each instruction
 - Adding More Executing units (e.g., Multipliers)
 - Increase the number of instructions that can be issued and executed in every cycle
- Highly specialized hardware in core (such as ARM processors)
- Co-processors (such as Image Signal Processor (ISP))
- Multi-Core DSPs

Example: TI OMAP Chip

Support Features:

- Integrates a TMS320C55x™ DSP core with an ARM GPP on a Single Chip
- OMAP 4 (released December 2010) Architecture includes a dedicated
 - 32-bit Dual-channel LPDDR2 memory technology
 - Uses dual-core ARM Cortex-A9s
 - Uses a PowerVR SGX540 integrated 3D graphics accelerator
 - IVA3 multimedia hardware accelerator with a programmable DSP that enables 1080p Full HD and multi-standard video encode/decode



The Galaxy Nexus, example of a smartphone with an OMAP 4460 SoC

- Comparison: DSP, FPGA, ASIC

“A tradeoff between microcontroller, DSP, FPGA and ASIC technologies”, EE Times 2009.

“DSP versus FPGA”, Electronics Weekly 2012.

“Are FPGA ready to replace ASIC”, Design Automation Conference (DAC'12)2012 .

Processor Selection Criteria

- Wide range of different platforms are available, which one to select?
- It depends about the application: what is the most important criteria?
 - Speed.
 - Memory bandwidth.
 - Cost.
 - Ease of use of development tools.
 - Packaging options.
 - On-chip integration.
 - Power consumption.

Processor Selection Criteria

- Use of available benchmarks:
 - BDTI kernel benchmarks.
 - BDTI application benchmarks.
- Use a hierarchical approach to pick a processor
 - List your requirements.
 - Start with critical criteria; and prioritize the remaining ones.
 - Trade-offs may be required.

Mini Assignment

- Search the Internet for the state-of-the-art processors of the platforms we covered; ASIC, FPGA, and DSP in terms of:
- Architecture
- Performance
- Power
- Cost
- Market share
- Leading manufactures